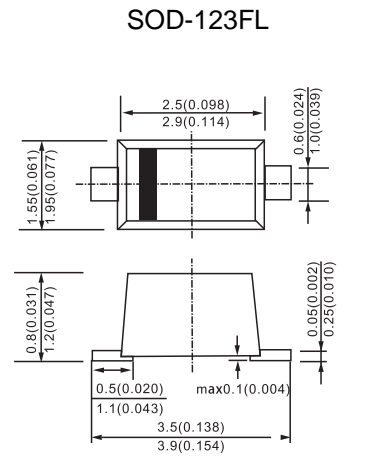


FEATURES

- For surface mounted applications
- Low profile package
- Ideal for automated placement
- Glass Passivated Chip Junction
- High temperature soldering : 260°C / 10 seconds at terminals
- Pb free product : 99% Sn can meet RoHS environment substance directive request

MECHANICAL DATA

- Case: JEDEC SOD-123FL, Molded plastic over passivated junction.
- Terminals: Solderable per MIL-STD-750, Method 2026
- Polarity : Color band denotes positive end (cathode)
- standard Packaging : 8mm tape (EIA-481)
- Approx. Weight: 0.0168 gram



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%

Rating	Test condition	Symbol	RS1001FL	RS1002FL	RS1004FL	RS1006FL	RS1008FL	Units	
Maximum repetitive peak reverse voltage		V_{RRM}	100	200	400	600	800	V	
Maximum RMS voltage		V_{RMS}	70	140	280	420	560	V	
Maximum DC blocking voltage		V_{DC}	100	200	400	600	800	V	
Maximum average forward rectified current	$T_{JP}=65^{\circ}C$ $T_A=45^{\circ}C$	$I_{F(AV)}$	1.4				0.5		A
Maximum instantaneous forward voltage	0.7A	V_F	1.15						V
Maximum DC reverse current at rated DC blocking voltage	$T_A=25^{\circ}C$ $T_A=125^{\circ}C$	I_R	10				50		μA
Thermal resistance junction to ambient air		$R_{\theta JA}$	180						K/W
Operating junction and storage temperature range		T_J, T_{STG}	-50 TO + 150						$^{\circ}C$
Reverse recovery time	$I_F=0.5A$ $I_R=1A$ $t_{rr}=0.25A$	t_{rr}	150			250	500	nS	
Typical capacitance	4V,1MHz	C_j	9						pF

RATINGS AND CHARACTERISTIC CURVES

RS1001FL THRU RS1008FL

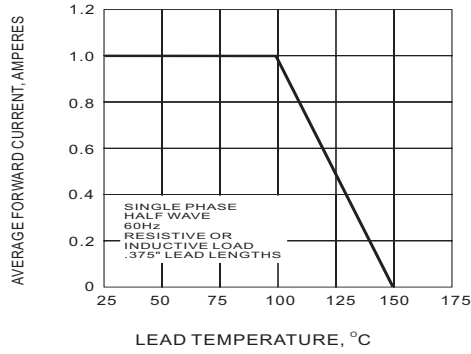


Fig.1 FORWARD CURRENT DERATING CURVE

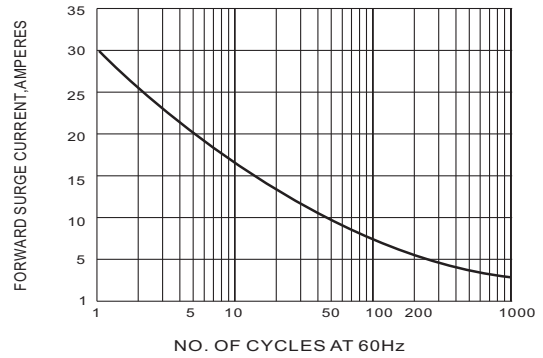


Fig.2 PEAK FORWARD SURGE CURRENT

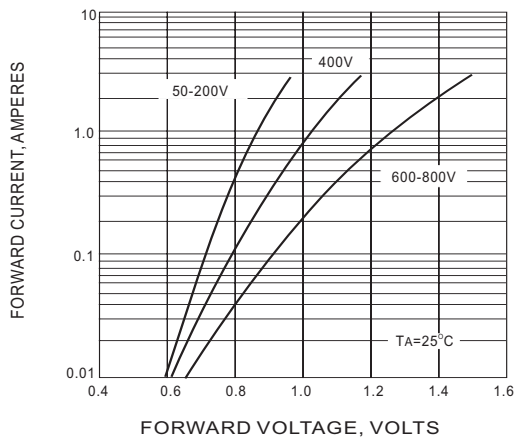


Fig.3 FORWARD CHARACTERISTICS

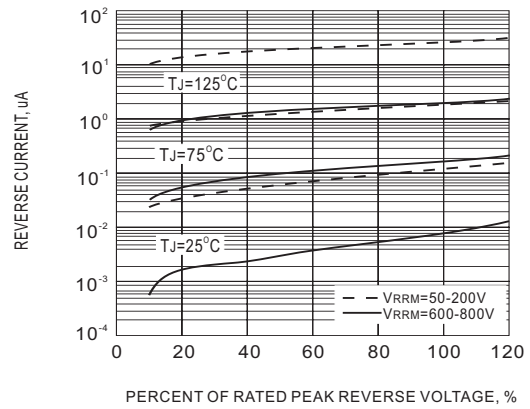


Fig.4 TYPICAL REVERSE CHARACTERISTICS

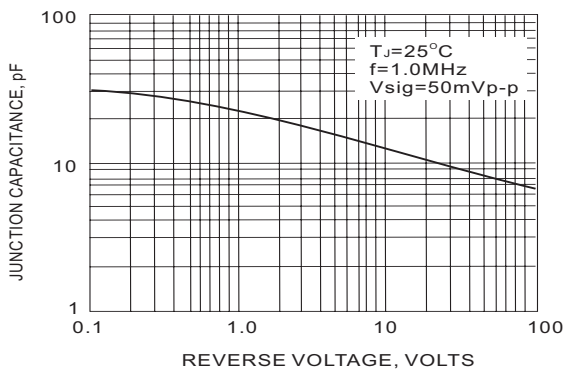


Fig.5 TYPICAL JUNCTION CAPACITANCE